

#### 3.2x1.6mm SMD CHIP LED LAMP

KP-3216SURCK

HYPER RED

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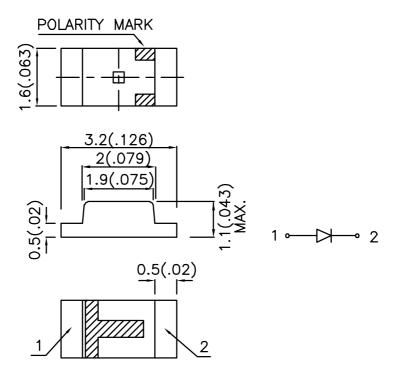
#### **Features**

- •3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS/REEL.
- •RoHS COMPLIANT.

#### Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

#### **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- Tolerance is ±0.2(0.0079") unless otherwise noted.
   Specifications are subject to change without notice.

**SPEC NO: DSAB5338 REV NO: V.6** DATE: MAR/18/2005 APPROVED: J. Lu **CHECKED: Allen Liu DRAWN: Y.CHENG** 

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#### **Selection Guide**

Part No.	art No. Dice Lens Type		Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Тур.	2 <del>0</del> 1/2
KP-3216SURCK	HYPER RED (InGaAIP)	WATER CLEAR	50	150	120°

Note:

### Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD	Dominant Wavelength	Hyper Red	635		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
IR	Reverse Current	Hyper Red		10	uA	VR = 5V

### Absolute Maximum Ratings at Ta=25°C

Parameter	Hyper Red	Units	
Power dissipation	170	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	185	mA	
Reverse Voltage	5	V	
Operating / Storage Temperature	-40°C To +85°C		

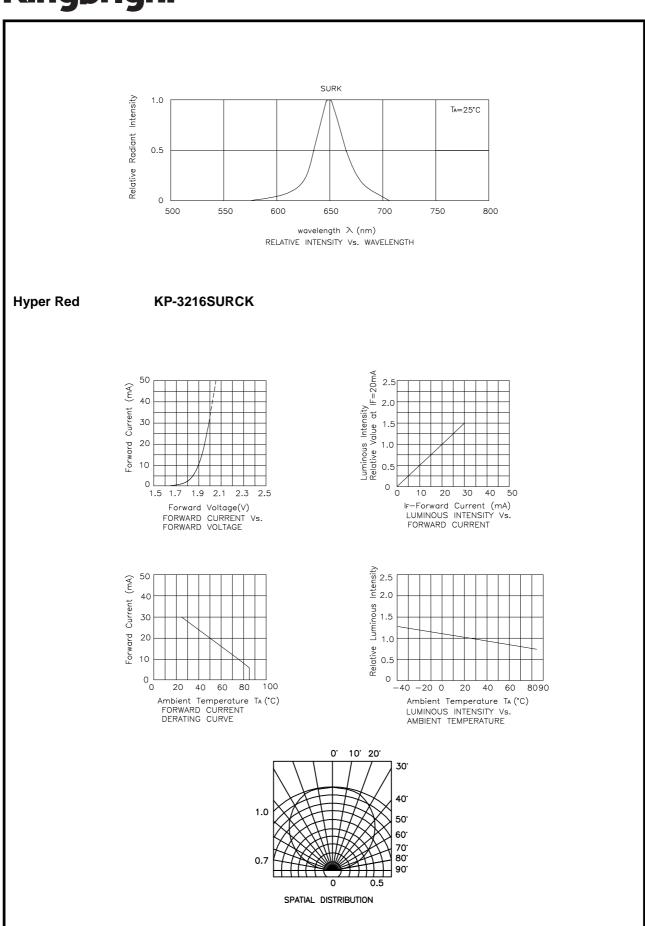
Note

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 $<sup>1.\,\</sup>theta1/2$  is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

<sup>1. 1/10</sup> Duty Cycle, 0.1ms Pulse Width.

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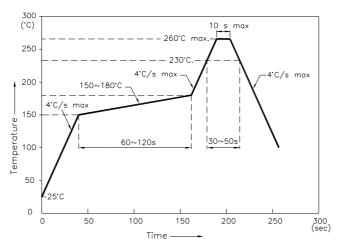


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## **Kingbright**

#### **KP-3216SURCK**

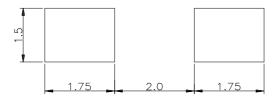
Reflow Soldering Profile For Lead-free SMT Process.



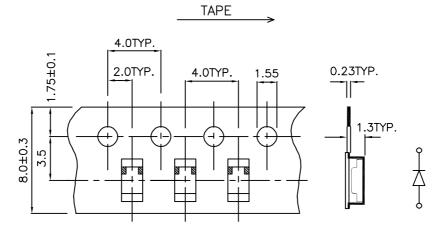
#### NOTES:

- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it  $\,$  is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

### Recommended Soldering Pattern (Units: mm)



### Tape Specifications (Units: mm)



#### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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